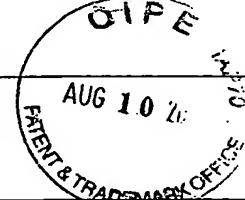
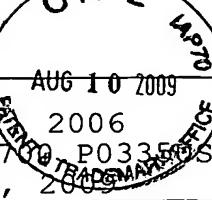


INFORMATION  
DISCLOSURE  
CITATION

Applicant: Katsuyuki TSUCHIDA et al  
Ser. No.: 10/588 686  
Conf. No.: 9917  
Group: 1795

Filed: August 4, 2006  
Atty. Docket No.: 470076000000000000  
Date: August 4, 2009



FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.	Country Code - Document Number - Kind Code	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Trans.
	AA	JP 2002-508452	03-19-2002		includes English language abstract
	AB	JP 2002-506927	03-05-2002		includes English language abstract
	AC	JP 63-310989	12-19-1988	Shimamura, et al.	includes English language abstract
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NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	(Include Author, Title, Date, Pages, Etc.)
	AG	Japanese language Office Action in a counterpart foreign application dated July 6, 2009 (4 sheets)
	AH	Japanese language Office Action in a counterpart foreign application dated May 8, 2009 (4 sheets)
	AI	Japanese language Office Action in a counterpart foreign application dated April 9, 2009 (3 sheets)
	AJ	``Voltammetric and morphological characterization of copper electrodeposition from non-cyanide electrolyte'', M.R.H. DE ALMEIDA, et al., Journal of Applied Electrochemistry, Vol. 32, pp. 763-773 (2002)

EXAMINER SIGNATURE

DATE CONSIDERED

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